

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TAE SUNG KIM	03/11/2020
HYEONG SIK YUN	03/11/2020
WOO CHUL SHIN	03/11/2020
JOON WOON LEE	03/11/2020
RECEIVING PARTY DATA	
Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.
Street Address:	MAEYOUNG-RO 150 (MAETAN-DONG), YOUNGTONG-GU
City:	SUWON-SI, GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17726888
CORRESPONDENCE DATA	
Fax Number:	(202)739-3001
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2027393000
Email:	patents@morganlewis.com, christine.peoples@morganlewis.com
Correspondent Name:	HOSANG LEE
Address Line 1:	MORGAN, LEWIS & BOCKIUS LLP
Address Line 2:	1111 PENNSYLVANIA AVENUE NW
Address Line 4:	WASHINGTON, D.C. 20004
ATTORNEY DOCKET NUMBER:	123193-8781-US
NAME OF SUBMITTER:	RAYMAR FARID
SIGNATURE:	/raymar farid/
DATE SIGNED:	04/22/2022
Total Attachments: 2	
source=123193-8781-US-Declaration-Assignment#page1.tif	
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other relevant treaties;

I hereby authorize and request the United States Patent and Trademark Office and officials in patent offices in foreign countries to issue any and all of said Letters Patent to the ASSIGNEE as the assignee of my entire right, title, and interest in and to the same, for the sole use and benefit of the ASSIGNEE, and its lawful successors and assigns, to the full end of the term for which said Letters Patent may be granted;

I hereby grant the attorney of record the power to insert on this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office or other authority for recordation of this document;

I hereby covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment; and

Further, I hereby further covenant and agree that I will, without further consideration, communicate with the ASSIGNEE, and its lawful successors and assigns, any facts known to me respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said ASSIGNEE, and its lawful successors or assigns, execute all divisional, continuation, continuation-in-part, and reissue applications, make all rightful oaths and generally do everything possible to aid the ASSIGNEE, and its lawful successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the ASSIGNEE, and its lawful successors and assigns.

IN TESTIMONY WHEREOF, I have hereunto set my hands.

NAME OF INVENTOR (Full Legal Name) : Tae Sung KIM

Signature: _____

김태성

Date: 2020.03.11

NAME OF INVENTOR (Full Legal Name) : Hyeong Sik YUN

Signature: _____

윤형식

Date: 2020.03.11

NAME OF INVENTOR (Full Legal Name) : Woo Chul SHIN

Signature: _____

신우철

Date: 2020.03.11

NAME OF INVENTOR (Full Legal Name) : Joon Woon LEE

Signature: _____

이준원

Date: 2020.03.11

Morgan, Lewis & Boekius LLP

PATENT

RECORDED: 04/22/2022

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